



DOCKET NO.: 209211US0

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF: :
Yukihiko SHIRAKAWA : GROUP ART UNIT: 2879
SERIAL NO.: 09/866,732 :
FILED: May 30, 2001 : EXAMINER: HARPER, H.
FOR: THIN-FILM EL DEVICE, AND ITS FABRICATION PROCESS

RECEIVED
JUL -3 2003
TECHNOLOGY CENTER 2800

#14B Annot
M. Brunson
7/17/03

AMENDMENT AND REQUEST FOR RECONSIDERATION

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated March 31, 2003, please reconsider the application in view of the following amendment and remarks.

IN THE CLAIMS

Please add the following new Claims.

6. (New) The thin-film EL device according to Claim 1, wherein said electrically insulating substrate maintains a given heat-resistant strength without contaminating said patterned electrode layer and said dielectric layer.

31 7. (New) The thin-film EL device according to Claim 1, wherein said electrically insulating substrate is selected from the group consisting of alumina (Al_2O_3), quartz glass (SiO_2), magnesia (MgO), forsterite ($2\text{MgO} \cdot \text{SiO}_2$), steatite ($\text{MgO} \cdot \text{SiO}_2$), mullite ($3\text{Al}_2\text{O}_3 \cdot 2\text{SiO}_2$), beryllia (BeO), zirconia (ZrO_2), aluminum nitride (AlN), silicon nitride (SiN), silicon carbide (SiC), crystallized glass, high heat-resistance glass, green sheet glass substrates and enameled metal substrates.